SIPE	Complete if Known		
/O'' > %	Application Number	10/790,572	
AUS 1 2 2004	Filing Date	March 1, 2004	
	First Named Inventor	Moon-Sook Lee	
	·Group Art Unit	2815	
	Examiner Name	Unknown A. WILSON	
(A)	Attomey Docket Number	5649-1267	
,	AUG 1 2 2004	AUG 1 2004 First Named Inventor Group Art Unit Examiner Name Attorney Docket Number	

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OTHER NON PATENT LITERATURE DOCUMENTS						
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published				
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Examiner Signature Date Considered						

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.